



Title of Change:	Qualifying ASEM as second source for Assembly and Test for 5x6 PQFN parts	
Proposed first ship date:	14 May 2019	
Contact information:	Contact your local ON Semiconductor Sales Office or < Ravi.Savanur@onsemi.com >	
Samples:	Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Lalan.ortega@onsemi.com >.	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com >	
Change Part Identification:	Affected parts will have marking code which identifies the assembly location	
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Cebu Philippines	External Foundry/Subcon Sites: ASE Malaysia
Description and Purpose:		
<p>To increase capacity, ASEM is being qualified for Assembly and Test of all 5x6 PQFN parts. Currently parts are assembled and tested at OSPI Cebu, Philippines.</p> <p>After the change the parts will be assembled and tested at both facilities. The marking will have the assembly/test location encoded</p> <p>"There are no product material changes as a result of this change"</p> <p>"There is no product marking change as a result of this change"</p>		

**Reliability Data Summary:**

QV DEVICE NAME FDMF3180
 RMS #'s F48009, W48059
F52270, W52271
 PACKAGE PQFN39

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C, 100 % max rated Vcc	1008 hrs	0 / 231
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0 / 231
TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc	0 / 231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0 / 231
AC	JESD22-A102	121°C, 100% RH, 15.5psig, unbiased	96 hrs	0 / 231
IOL (FET1)	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0 / 231
IOL (FET2)			15000 cyc	0 / 231
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		0 / 1155
SAT	JEDEC STD 035	Pre and Post MSL 1		0 / 25
RSH	JESD22- B106	Ta = 265C, 10 sec		0 / 90
SD	JSTD002	Ta = 245C, 10 sec		0 / 45
PD	JESD22-B100	Per POD, case 751EB		0 / 30
CDPA	MILSTD750 Method 2037	Wire Pull after TC500 cycles		0 / 18
CDPA	MILSTD750 Method 2037	Wire Pull after HTSL 1008hrs		0 / 18

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (offthe shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FDMF3160	FDMF3180
FDMF3170	
FDMF3172	
FDMF3180	